

SOT796A

leadless surface mounted package; plastic cap; 18 terminations

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QMAN18
Package type industry code	QMAN18
Package style descriptive code	QMAN (quad microelectronic assembly; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.8	-	10	10.2	mm
E	package width	7.8	-	8	8.2	mm
A	seated height	[tbd]	-	1.6	1.6	mm
n ₂	actual quantity of termination	-	-	18	-	



2. Package outline

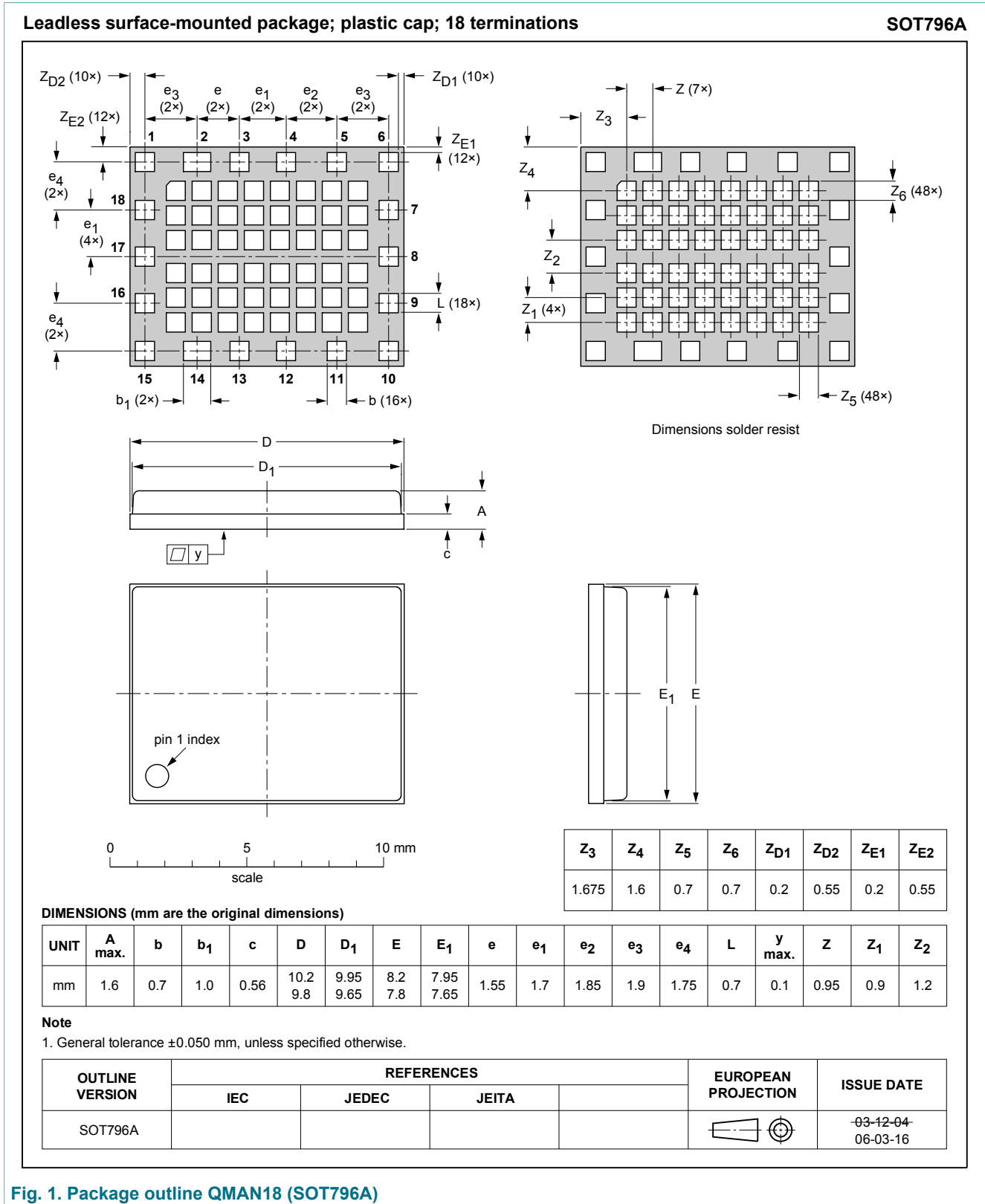


Fig. 1. Package outline QMAN18 (SOT796A)

3. Legal information

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